Unconfirmed Meeting Minutes: IEEE 802.3 Enhancements to Point-to-Point Single Pair Ethernet Study
Group

May 12, 2021

Teleconference

Prepared by Jon Lewis

Meeting was called to order 12 May 2021 at 9:05 am by Mr. George Zimmerman, Study Group chair Attendance for the meeting is listed in Appendix A

The Chair reviewed the agenda.

Please see: https://www.ieee802.org/3/SPEP2P/public/agenda 3SPEP2P 01a 05122021.pdf
Jon Lewis was appointed recording secretary for this meeting.

MOTION #1: Approve the agenda as shown in

https://www.ieee802.org/3/SPEP2P/public/agenda_3SPEP2P_01a_05122021.pdf

M: Matthias Fritsche S: Bob Voss

Motion Passes by Unanimous Consent

MOTION #2: Approve the minutes from April 28, 2021 as posted.

https://www.ieee802.org/3/SPEP2P/public/Unconfirmed%20Minutes SPE-P2P 0428.pdf

M: Chad Jones S: Matthias Fritsche

Motion Passes by Unanimous Consent

The Chair continued with the presentation agenda:

- Mr. Zimmerman asked if anyone was attending from the press including those who would run a public blog on this meeting there were no indications from the group.
- Mr. Zimmerman noted that there should be no recording or photography without permission.

IEEE Patent Policy, Mr. Zimmerman asked if anyone had not seen the patent slides (slides 11-12) recently, none responded. Mr. Zimmerman then reviewed the Study Group patent slides with the group. Mr. Zimmerman reviewed the IEEE SA Copyright slides (slides 13-14) and the IEEE SA Participation slides (slides 15-17)

Mr. Zimmerman reviewed the goals for the meeting, access to the reflector and website, and ground rules.

LIAISONS

The Chair moved to liaisons and noted that there were none for the Study Group at this time.

Attendance, Mr. Zimmerman advised the group of the IEEE meeting attendance tool and procedures and proceeded to demonstrate to the group.

The Chair completed review of the agenda.

PRESENTATIONS

The Chair then moved to the presentations for the meeting.

Title: Strawman Draft PAR for 10 Mb/s TSN Enhancements (d3) – pre meeting

URL: https://www.ieee802.org/3/SPEP2P/public/Strawman_PAR_10Mb_TSN_Enh_d3.pdf
Presenter: George Zimmerman, CME Consulting/ADI, APL Group, CommScope, Cisco Systems,

Marvell, and SenTekse

Title: Strawman Draft CSD for 10 Mb/s TSN Enhancements

URL: https://www.ieee802.org/3/SPEP2P/public/Strawman CSD 10Mb TSN Enh d1.pdf

Presenter: George Zimmerman, CME Consulting/ADI, APL Group, CommScope, Cisco Systems,

Marvell, and SenTekse

Title: Possible Objectives for 10 Mb/s TSN Enhancements

URL: https://www.ieee802.org/3/SPEP2P/public/zimmerman 3SPEP2P 01 04282021.pdf

Presenter: George Zimmerman, CME Consulting/ADI, APL Group, CommScope, Cisco Systems,

Marvell, and SenTekse

Straw Poll #1: I support adding support for half duplex 10 Mb/s SPE PHYs to clause 99

Yes: 5; No: 10; Abstain: 13

Title: Strawman Draft PAR for 10 Mb/s TSN Enhancements

URL: https://www.ieee802.org/3/SPEP2P/public/Fritsche 3SPEP2P 01 05122021.pdf

Presenter: Matthias Fritsche, Harting Technology Group

Discussion time for the last presentation was cut short due to time constraints and the Chair asked if the discussion could be moved to the reflector and that this would be added to the next meeting agenda.

Mr. Zimmerman noted that the group had exhausted the available time and adjourned the meeting.

THE MEETING ADJOURNED AT 12:00 PM EDT

Appendix A: Attendees at the IEEE 802.3 Enhancements to Point-to-Point Single Pair Ethernet Study Group, May 12, 2021.

Name	Employer	Affiliation
Brychta, Michal	Analog Devices Inc.	Analog Devices Inc.
Buchanan, Rory	ON Semiconductor	ON Semiconductor
Chiou, Dachen	DAN-CHIEF Technology Co., Ltd.	DAN-CHIEF Technology Co., Ltd.
Dearing, Mark	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Fischer, Peter		BKS Kabel-Service AG
Fitzgerald, Niall	Analog Devices	Analog Devices Inc.
Franchuk, Brian	Emerson Automation Solutions	Emerson Automation Solutions
Fritsche, Matthias	HARTING Technologie Gruppe	HARTING Electronics GmbH
Graber, Steffen	Pepperl+Fuchs SE	Pepperl+Fuchs SE
Haasz, Jodi	IEEE - Institute of Electrical and Electronics	IEEE Standards Association (IEEE-SA)
	Engineers	
Han, Ruibo	CMCC	CMCC
Hess, Dave	Cord Data	Cord Data
Horrmeyer, Bernd	Phoenix Contact	Phoenix Contact
Huh, Woojung	Microchip	Microchip
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Kabra, Lokesh	Synopsys, Inc.	Synopsys, Inc.
Lackner, Hans	QoSCom GmbH	QoSCom - Quality in Communications - GmbH
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Lewis, Jon	Dell Technologies	Dell Technologies
McCarthy, Mick	Analog Devices Inc.	Analog Devices Inc.
Murray, Brian	Analog Devices	Analog Devices
Nikolich, Paul	Paul Nikolich	SAMSUNG
Ostertag, Martin	ZHAW	ZHAW, APL Project
Potterf, Jason	Cisco Systems, Inc.	Cisco Systems, Inc.
Rajai, Kalpesh	Texas Instruments	Texas Instruments Inc.
Schicketanz, Dieter	Self	CONSULTANT; Reutlingen University
Stewart, Heath	Analog Devices	Analog Devices
Sun, Wensheng	Marvell	Marvell
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT
Voss, Robert	Panduit Corp.	Panduit Corp.
Withey, James	Fluke Corporation	Fluke Corporation
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Xu, Dayin	Rockwell Automation	Rockwell Automation
Zimmerman, George	CME Consulting	CME Consulting/ADI, APL Group, CommScope,
		Cisco Systems, Marvell, and SenTekse